Abstract

A method of fabricating a SIM card is disclosed. The method comprises providing a first mould part, a second mould part and a third mould part, disposing the first mould part and the third mould part adjacent each other so as to define a first mould for moulding a first SIM card portion, and moulding the first SIM card portion using the first mould. The method also comprises disposing the second mould part and the third mould part adjacent each other so as to define a second mould for moulding a second SIM card portion, the second mould containing the first moulded SIM card portion, and moulding the second SIM card portion using the second mould and the first SIM card portion contained in the second mould such that the second SIM card portion is moulded around the first SIM card portion. The first mould is configured such that when the first SIM card portion is moulded and the second SIM card portion subsequently moulded around the first SIM card portion, the first SIM card portion is engageable with and disengageable from the second SIM card portion.

Fig. 12